

Application No.: 09/998935

Case N.: 56196US011

REMARKS

Claims 1-33 are pending. Claims 2 and 3 have been canceled. Claims 16-33 have been withdrawn from consideration. Claims 1 and 15 are amended. Support for these amendments can be found, for example, in original claims 2 and 3.

§ 103 Rejections

In order to present a prima facie case of obviousness, three basic criteria must be met. First, there must be some suggestion or motivation, either in the references themselves or in the knowledge generally available to one of ordinary skill in the art, to modify the reference or to combine reference teachings. Second, there must be a reasonable expectation of success. Finally, the prior art reference must teach or suggest all the claim limitations. The teaching or suggestion to make the claimed combination and the reasonable expectation of success must both be found in the prior art, and not based on applicant's disclosure.

Claims 1-9 and 1-15 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Yau et al. in view of Everaerts et al. Claim 10 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yau et al. in view of Everaerts et al. as applied to claim 1 above, and further in view of Peloquin et al. Claim 10 also stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yau et al. in view of Everaerts et al. as applied to claim 1, and further in view of the abstracts of both JP-02178379A and JP-03281585A.

The Examiner states that the minor amount of materials present in Yau would not alter the basic and novel features of the adhesive. However, Applicant respectfully directs the Examiner to the Yau patent at column 3, lines 31-38. The present claims have been amended to require that the adhesive composition, when applied to a copper-containing or glass substrate at a thickness of 0.0008 inch and exposed to a temperature of 180°C for 30 minutes, is cleanly removable following heat exposure. The Yau patent specifically states that the adhesive survives elevated temperatures for periods of 5 seconds, preferably 20 seconds. Therefore, an additive of Yau, not in the present invention, alters the basic and novel features of the present invention. Yau fails to teach each and every element of the presently claimed invention. The addition of the secondary references cited fail to remedy this deficiency in Yau.

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The rejections of claims 1-15 under 35 U.S.C. § 103(a) as being unpatentable over Yau as a primary reference have been overcome and should be withdrawn.

In view of the above, it is submitted that the application is in condition for allowance. Reconsideration of the application is requested.

Allowance of claims 1 and 4-15, as amended, at an early date is solicited.

Respectfully submitted,

March 17, 2003

Date

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CHB/spg
09/196US011 AMEND 2

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Version with markings to show amendments made:

1. (Twice Amended) An adhesive article comprising:

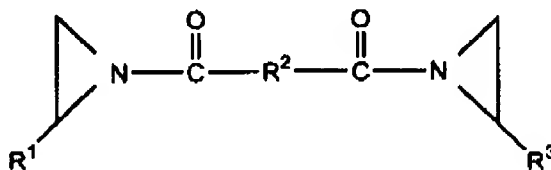
(1) a backing; and

(2) a pressure sensitive adhesive composition on said backing,

said composition consisting essentially of the reaction product of:

(A) a copolymer comprising the reaction product of (a) a (meth)acrylate ester of a non-tertiary alcohol in which the alkyl group contains between 1 and 8 carbon atoms, inclusive, and whose homopolymer has a glass transition temperature no greater than about 0°C; and (b) a carboxylic acid-functional, ethylenically unsaturated co-monomer; and

(B) a bis-amide crosslinking agent having the formula:



where R^1 and R^3 independently, are selected from the group consisting of H and C_nH_{2n+1} where n is an integer ranging from 1 to 5, and R^2 is a divalent radical selected from the group consisting of benzeno ($-C_6H_4-$), substituted benzeno, triazine, C_mH_{2m} where m is an integer ranging from 1 to 10, and combinations thereof,

the relative amounts of said co-monomer and said crosslinking agent being selected such that (i) the ratio of the number of equivalents of amide groups to the number of equivalents of carboxylic acid groups is at least about 0.1,

wherein the pressure sensitive adhesive composition comprises no greater than 10% by weight of a tackifier and no greater than 2% by weight of a plasticizer,
wherein said composition, when applied to a copper-containing or glass substrate at a thickness of 0.0008 inch and exposed to a temperature of 180°C for 30 minutes, is cleanly removable following heat exposure.

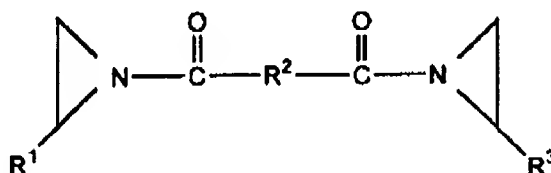
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15. (Twice Amended) A pressure sensitive adhesive composition consisting essentially of the reaction product of:

(A) a copolymer comprising the reaction product of (a) a (meth)acrylate ester of a non-tertiary alcohol in which the alkyl group contains between 1 and 8 carbon atoms, inclusive, and whose homopolymer has a glass transition temperature no greater than about 0°C; and (b) a carboxylic acid-functional, ethylenically unsaturated co-monomer; and

(B) a bis-amide crosslinking agent having the formula:



where R^1 and R^3 independently, are selected from the group consisting of H and C_nH_{2n+1} where n is an integer ranging from 1 to 5, and R^2 is a divalent radical selected from the group consisting of benzeno ($-C_6H_4-$), substituted benzeno, triazine, C_mH_{2m} where m is an integer ranging from 1 to 10, and combinations thereof,

the relative amounts of said co-monomer and said crosslinking agent being selected such that (i) the ratio of the number of equivalents of amide groups to the number of equivalents of carboxylic acid groups is at least about 0.1,

wherein the pressure sensitive adhesive composition comprises no greater than 10% by weight of a tackifier and no greater than 2% by weight of a plasticizer,

wherein said composition, when applied to a copper-containing or glass substrate at a thickness of 0.0008 inch and exposed to a temperature of 180°C for 30 minutes, is cleanly removable following heat exposure.